

**HYSOL GR910**
(LMC20572-C)

Jun. 2019

PRODUCT DESCRIPTION

HYSOL GR910 provides the following product characteristics:

Technology	Epoxy
Appearance	Black
Filler Type	Spherical silica
Filler Weight, %	88±1
Filler cut	75µm
Typical Package(s)	Memory BGA, LGA
Product Benefits	<ul style="list-style-type: none">• Halogen free• High fluidity• Low shrinkage• Advanced warpage control• Good electrical performance

HYSOL GR910 is a green molding compound designed for BGA/LGA.

HYSOL GR910 meets UL 94 V-0 Flammability at 1/8 inch thickness.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Property	Typical Value
Spiral Flow, @ 175°C, inches	80
Gel Time @ 175°C, seconds	47
Shelf Life @ 5°C, days	183
Specific Gravity, g/cm ³	2.01

TYPICAL PROCESS DATA

Handling	Typical Value
Preheat Temperature, conventional mold, °C	70 to 90
Molding Temperature, °C	170 to 185
Molding Pressure, Kg/cm ²	40 to 85
Transfer Time, seconds	7 to 15
Curing Time, seconds	100 to 150
Post Cure Time, hours	4 to 8

HYSOL GR910 has been formulated to provide the best possible moldability and as wide a molding latitude as possible. Although molding and curing conditions will vary from situation to situation, recommended starting ranges are shown above.

TYPICAL PROPERTIES OF CURED MATERIAL

All measurements taken at 175°C unless otherwise noted. All physical, electrical and analytical measurements taken on specimens cured for 2 minutes @175°C with post cure of 6 hours @ 175°C, unless otherwise specified.

Physical Properties Property Typical Value

Glass Transition Temperature (Tg), °C	130
Coefficient of Thermal Expansion, ppm/°C:	
Below Tg	9
Above Tg	33
Flexural Modulus @ 25°C, N/mm ²	22000
Flexural Strength @ 25°C, N/mm ²	160
Moisture Absorption, 24 hours PCT, %	0.3

Application Specific Properties

Thermal Conductivity, W/(m-K)	0.9
Volume resistivity @ 21°C, 500 V, Ω-cm	3×10 ¹⁶

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 5°C. Storage greater than 5°C can adversely affect product properties. Material removed from containers may be contaminated during use. Do not return products to the original container. Hysol Huawei Electronics Co., Ltd. cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact Hysol Huawei Electronics Co., Ltd. Technical Service Center or Customer Service Representative.

NOTE

This product is a developmental product. It is not now, and may not be in the future, commercially available. The properties of the uncured material and the physical properties of the cured material have been established as a point of reference only. The information provided in this Lab Data Sheet (LDS) including the recommendations for use and application of the product are based on our best knowledge and experience of the product as at the date of this LDS. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide.

The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Hysol Huawei Electronics Co., Ltd. patents that may cover such processes or compositions. This product may contain materials that are not regulatory listed on TSCA, EINECs and other global inventories.

Hysol Huawei Electronics Co., Ltd. cannot assume responsibility for the results obtained by others over whose methods Hysol Huawei Electronics Co., Ltd. has no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof.

In light of the foregoing, Hysol Huawei Electronics Co., Ltd. **specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Hysol's products. Hysol specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.**